

**Assembly Transfer of Select BGA Products and Conversion
to CSP_BGA to STATS ChipPAC Korea**

**Qualification Plan Summary for
CSP_BGA at STATS ChipPAC Korea**

TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 32	Nov 2020
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Nov 2020
Temperature Humidity Bias (THB)*	JEDEC <i>JESD22-A101</i>	3 x 32	Nov 2020
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 32	Nov 2020
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A102</i>	3 x 32	Nov 2020

* Preconditioned per JEDEC/IPC J-STD-020.